

AO4822

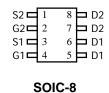
## **Dual N-Channel Enhancement Mode Field Effect Transistor**

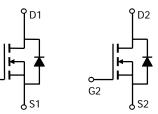
## **General Description**

The AO4822 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as a load switch or in PWM applications. *Standard Product AO4822 is Pb-free (meets ROHS & Sony 259 specifications). AO4822L is a Green Product ordering option. AO4822 and AO4822L are electrically identical.* 

## Features

$$\begin{split} V_{\text{DS}} & (\text{V}) = 30\text{V} \\ I_{\text{D}} = 8.5\text{A} \; (\text{V}_{\text{GS}} = 10\text{V}) \\ \text{R}_{\text{DS}(\text{ON})} < 16\text{m}\Omega \; (\text{V}_{\text{GS}} = 10\text{V}) \\ \text{R}_{\text{DS}(\text{ON})} < 26\text{m}\Omega \; (\text{V}_{\text{GS}} = 4.5\text{V}) \end{split}$$





Parameter		Symbol	Maximum	Units		
Drain-Source Voltage		V <sub>DS</sub>	30	V		
Gate-Source Voltage		V <sub>GS</sub>	±20	V		
Continuous Drain	T <sub>A</sub> =25°C		8.5			
Current <sup>A</sup>	T <sub>A</sub> =70°C	I <sub>D</sub>	6.6	А		
Pulsed Drain Current <sup>B</sup>		I <sub>DM</sub>	30			
	T <sub>A</sub> =25°C	D	2	w		
Power Dissipation	T <sub>A</sub> =70°C	- P <sub>D</sub>	1.28	v		
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C		

Thermal Characteristics									
Parameter	Symbol	Тур	Max	Units					
Maximum Junction-to-Ambient <sup>A</sup>	t ≤ 10s	D	48	62.5	°C/W				
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State	$R_{ ext{ heta}JA}$	74	110	°C/W				
Maximum Junction-to-Lead <sup>C</sup>	Steady-State	$R_{ ext{ heta}JL}$	35	40	°C/W				



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC F	PARAMETERS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V				1	μA
			TJ=52°C			5	μΑ
I <sub>GSS</sub>	Gate-Body leakage current	$V_{DS}$ =0V, $V_{GS}$ = ±20V				100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS}$ $I_{D}=250\mu A$		1	1.8	3	V
I <sub>D(ON)</sub>	On state drain current	$V_{GS}$ =10V, $V_{DS}$ =5V		30			А
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A			13.4	16	mΩ
			T <sub>J</sub> =125°C		20	25	1115.2
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A			21	26	mΩ
<b>g</b> fs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =8.5A			23		S
$V_{SD}$	Diode Forward Voltage	I <sub>S</sub> =1A,V <sub>GS</sub> =0V			0.76	1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Cur	urrent				3	А
	PARAMETERS						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz			1040	1250	pF
C <sub>oss</sub>	Output Capacitance				180		pF
C <sub>rss</sub>	Reverse Transfer Capacitance				110		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz			0.7	0.85	Ω
SWITCHI	NG PARAMETERS						
Q <sub>g</sub> (10V)	Total Gate Charge				19.2	23	nC
Q <sub>g</sub> (4.5V)	Total Gate Charge	−−V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =8.5A			9.36	11.2	nC
$Q_{gs}$	Gate Source Charge				2.6		nC
Q <sub>gd</sub>	Gate Drain Charge				4.2		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =1.8Ω, R <sub>GEN</sub> =3Ω			5.2	7.5	ns
t <sub>r</sub>	Turn-On Rise Time				4.4	6.5	ns
t <sub>D(off)</sub>	Turn-Off DelayTime				17.3	25	ns
t <sub>f</sub>	Turn-Off Fall Time				3.3	5	ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =8.5A, dI/dt=100A/μ	I <sub>F</sub> =8.5A, dI/dt=100A/μs			21	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =8.5A, dl/dt=100A/μs			6.7	10	nC

A: The value of  $R_{BJA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}$ C. The value in any given application depends on the user's specific board design. The current rating is based on the t  $\leq$  10s thermal resistance rating. B: Repetitive rating, pulse width limited by junction temperature.

C. The R  $_{\rm 0JA}$  is the sum of the thermal impedence from junction to lead R  $_{\rm 0JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using  $80\mu s$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}$ C. The SOA curve provides a single pulse rating.

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